

#### For Reference Only – Not for Tooling Use

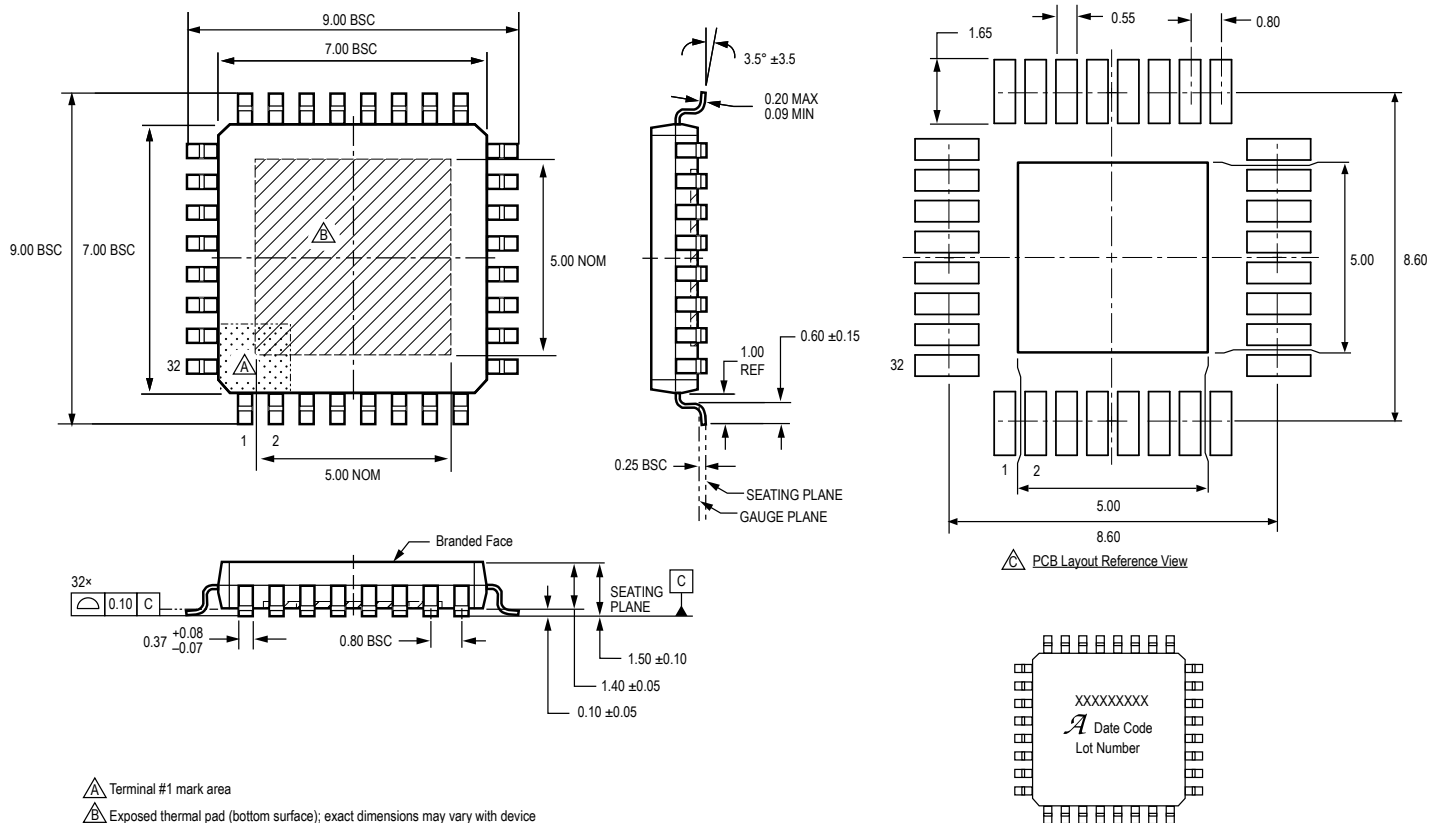
(Reference Allegro DWG-0000386, Rev. 5 or JEDEC MS-026 BBAHD)

NOT TO SCALE

Dimensions in millimeters

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions

Exact case and lead configuration at supplier discretion within limits shown



- △ Terminal #1 mark area
- △ Exposed thermal pad (bottom surface); exact dimensions may vary with device
- △ Reference land pattern layout (reference IPC7351 QFP80P900X900X160-32BM); adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)
- △ Branding scale and appearance at supplier discretion

- △ Standard Branding Reference View
- Line 1, 2, 3: Maximum 9 characters per line
- Line 1: Part Number
- Line 2: Logo A, 4-digit Date Code
- Line 3: Assembly Lot Number

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